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# IRF350/351/352/353 IRF350R/351R/352R/353R

N-Channel Power MOSFETs  
Avalanche Energy Rated\*

## Features

- 13A and 15.0A, 350V - 400V
- $r_{DS(on)} = 0.3\Omega$  and  $0.4\Omega$
- Single Pulse Avalanche Energy Rated\*
- SOA is Power-Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance

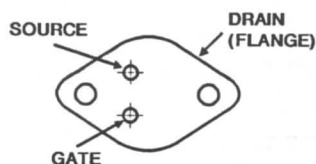
## Description

The IRF350, IRF351, IRF352, and IRF353 are n-channel enhancement-mode silicon-gate power field-effect transistors. IRF350R, IRF351R, IRF352R and IRF353R types are advanced power MOSFETs designed, tested, and guaranteed to withstand a specified level of energy in the breakdown avalanche mode of operation. All of these power MOSFETs are designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. These types can be operated directly from integrated circuits.

The IRF types are supplied in the JEDEC TO-204AA steel package.

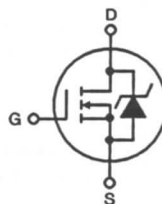
## Package

TO-204AA



## Terminal Diagram

N-CHANNEL ENHANCEMENT MODE



## Absolute Maximum Ratings ( $T_C = +25^\circ\text{C}$ ), Unless Otherwise Specified

	IRF350 IRF350R	IRF351 IRF351R	IRF352 IRF352R	IRF353 IRF353R	UNITS
Drain-Source Voltage (1) .....	$V_{DS}$ 400	350	400	350	V
Drain-Gate Voltage ( $R_{GS} = 20k\Omega$ ) (1) .....	$V_{DGR}$ 400	350	400	350	V
Continuous Drain Current					
$T_C = +25^\circ\text{C}$ .....	$I_D$ 15	15	13	13	A
$T_C = +100^\circ\text{C}$ .....	$I_D$ 9.0	9.0	8.0	8.0	A
Pulsed Drain Current (3) .....	$I_{DM}$ 60	60	52	52	A
Gate-Source Voltage .....	$V_{GS}$ $\pm 20$	$\pm 20$	$\pm 20$	$\pm 20$	V
Maximum Power Dissipation					
$T_C = +25^\circ\text{C}$ .....	$P_D$ 150	150	150	150	W
Linear Derating Factor .....	1.2	1.2	1.2	1.2	W/ $^\circ\text{C}$
Inductive Current, Clamped .....	$I_{LM}$ 60	60	52	52	A
(See Figure 14, $L = 100\mu\text{H}$ )					
Single Pulse Avalanche Energy Rating (4) .....	$E_{AS}^*$ 700	700	700	700	mJ
Operating and Storage Junction .....	$T_J, T_{STG}$ -55 to +150	-55 to +150	-55 to +150	-55 to +150	$^\circ\text{C}$
Temperature Range					
Maximum Lead Temperature for Soldering .....	$T_L$ 300	300	300	300	$^\circ\text{C}$
(0.063" (1.6mm) from case for 10s)					

### NOTES:

1.  $T_J = +25^\circ\text{C}$  to  $+150^\circ\text{C}$ .
2. Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
3. Repetitive rating: Pulse width limited by maximum junction temperature. See Transient Thermal Impedance Curve (Figure 5).

4.  $V_{DD} = 40\text{V}$ , starting  $T_J = +25^\circ\text{C}$ ,  $L = 5.66\text{mH}$ ,  $R_{GS} = 50\Omega$ ,  $I_{PEAK} = 15\text{A}$ . See Figure 15.

\*R Suffix Types Only

CAUTION: These devices are sensitive to electrostatic charge. Proper I.C. handling procedures should be followed.

NJ Semi-Conductors reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by NJ Semi-Conductors is believed to be both accurate and reliable at the time of going to press. However, NJ Semi-Conductors assumes no responsibility for any errors or omissions discovered in its use. NJ Semi-Conductors encourages customers to verify that datasheets are current before placing orders.



Quality Semi-Conductors

**IRF350, IRF351, IRF352, IRF353 IRF350R, IRF351R, IRF352R, IRF353R**

**Electrical Characteristics**  $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

CHARACTERISTIC	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
Drain-Source Breakdown Voltage IRF350/352, IRF350R/352R IRF351/353, IRF351R/353R	$BV_{DS}$	$V_{GS} = 0V, I_D = -250\mu A$	400	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.0	-	4.0	V
Gate-Source Leakage Forward	$I_{GSS}$	$V_{GS} = 20V$	-	-	100	nA
Gate-Source Leakage Reverse	$I_{GSS}$	$V_{GS} = -20V$	-	-	-100	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = \text{Max Rating}, V_{GS} = 0V$	-	-	250	$\mu A$
		$V_{DS} = \text{Max Rating} \times 0.8, V_{GS} = 0V, T_J = +125^\circ\text{C}$	-	-	1000	$\mu A$
On-State Drain Current (Note 2) IRF350/351, IRF350R/351R IRF352/353, IRF352R/353R	$I_{D(ON)}$	$V_{DS} > I_{D(ON)} \times r_{DS(ON)} \text{ Max}, V_{GS} = 10V$	15	-	-	A
			13	-	-	A
Static Drain-Source On-State Resistance (Note 2) IRF350/351, IRF350R/351R IRF352/353, IRF352R/353R	$r_{DS(ON)}$	$V_{GS} = 10V, I_D = 8.0A$	-	0.25	0.3	$\Omega$
			-	0.3	0.4	$\Omega$
			-	-	-	$\Omega$
Forward Transconductance (Note 2)	$g_{fs}$	$V_{DS} > I_{D(ON)} \times r_{DS(ON)} \text{ Max}, I_D = 8.0A$	8.0	10	-	S(1)
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 25V, f = 1.0\text{MHz}$	-	2000	-	pF
Output Capacitance	$C_{oss}$	See Figure 10	-	400	-	pF
Reverse Transfer Capacitance	$C_{rss}$		-	100	-	pF
Turn-On Delay Time	$t_{d(ON)}$	$V_{DD} \approx 180V, I_D = 8.0A, Z_o = 4.7\Omega$ See Figure 16. (MOSFET switching times are essentially independent of operating temperature)	-	-	35	ns
Rise Time	$t_r$		-	-	65	ns
Turn-Off Delay Time	$t_{d(OFF)}$		-	-	150	ns
Fall Time	$t_f$		-	-	75	ns
Total Gate Charge (Gate-Source + Gate-Drain)	$Q_g$	$V_{GS} = 10V, I_D = 18A, V_{DS} = 0.8V \text{ Max}$ Rating. See Figure 17 for test circuit. (Gate charge is essentially independent of operating temperature.)	-	79	120	nC
Gate-Source Charge	$Q_{gs}$		-	38	-	nC
Gate-Drain ("Miller") Charge	$Q_{gd}$		-	41	-	nC
Internal Drain Inductance	$L_D$	Measured between the contact screw on header that is closer to source and gate pins and center of center of die.	-	5.0	-	nH
Internal Source Inductance	$L_S$	Measured from the source lead, 6mm (0.25") from header and source bonding pad.	-	12.5	-	nH
Junction-to-Case	$R_{\theta JC}$		-	-	0.83	$^\circ\text{C/W}$
Case-to-Sink	$R_{\theta CS}$	Mounting surface flat, smooth and greased	-	0.1	-	$^\circ\text{C/W}$
Junction-to-Ambient	$R_{\theta JA}$	Free air operation	-	-	30	$^\circ\text{C/W}$

**Source Drain Diode Ratings and Characteristics**

Continuous Source Current (Body Diode)	$I_S$	Modified MOSFET symbol showing the integral reverse P-N junction rectifier.	-	-	15	A
Pulse Source Current (Body Diode) (Note 3)	$I_{SM}$		-	-	60	A
Diode Forward Voltage (Note 2)	$V_{SD}$	$T_J = +25^\circ\text{C}, I_S = 15A, V_{GS} = 0V$	-	-	1.6	V
Reverse Recovery Time	$t_{rr}$	$T_J = +150^\circ\text{C}, I_F = 15A, dI_F/dt = 100A/\mu s$	-	1000	-	ns
Reverse Recovered Charge	$Q_{RR}$	$T_J = +150^\circ\text{C}, I_F = 15A, dI_F/dt = 100A/\mu s$	-	6.6	-	$\mu C$
Forward Turn-on Time	$t_{ON}$	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$ .	-	-	-	-

NOTES: 1.  $T_J = +25^\circ\text{C}$  to  $+150^\circ\text{C}$

2. Pulse Test: Pulse width  $\leq 300\mu s$ ,  
Duty Cycle  $\leq 2\%$

3. Repetitive Rating: Pulse width limited by max.  
junction temperature. See Transient Thermal  
Impedance Curve (Figure 5)

4.  $V_{DD} = 40V$ , Start  $T_J = +25^\circ\text{C}$ ,  $L = 5.66\text{mH}$ ,  
 $R_{GS} = 50\Omega$ ,  $I_{PEAK} = 15A$  (See Figure 15)

